

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	733	257/678 and (chip or die or IC) and (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 11:30
2	BRS	137	257/678 and (chip or die or IC) and (electrode or pad or connection) and (wire or clip or conductive adj layer) and stack\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 12:05
3	BRS	156	257/678 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 15:08
4	BRS	233	257/686 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 16:09
5	BRS	68	257/688 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 16:15
6	BRS	15	257/689 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 16:18
7	BRS	237	257/700 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 16:33

	Type	Hits	Search Text	DBs	Time Stamp
8	BRS	111	257/701 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 16:39
9	BRS	63	257/718 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 16:41
10	BRS	266	257/723 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 16:50
11	BRS	183	257/724 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 16:55
12	BRS	46	257/725 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 16:55
13	BRS	43	257/726 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 16:57
14	BRS	54	257/727 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 16:58

	Type	Hits	Search Text	DBs	Time Stamp
15	BRS	15	257/731 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 17:00
16	BRS	8	257/732 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 17:00
17	BRS	5	257/733 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 17:01
18	BRS	199	257/777 and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 17:06
19	BRS	1609	257/\$.ccls. and (chip or die or IC) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 17:08
20	BRS	865	257/\$.ccls. and (chip or die or IC) and (front or top) adj surface same (electrode or pad or connection) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 17:34

	Type	Hits	Search Text	DBs	Time Stamp
21	BRS	385	361/\$.ccls. and (chip or die or IC) and (front or top) adj surface same (electrode or pad or connection) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 17:48
22	BRS	367	438/\$.ccls. and (chip or die or IC) and (front or top) adj surface same (electrode or pad or connection) and (back or bottom) adj surface same (electrode or pad or connection) and (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 17:56
23	BRS	4	6002167.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 17:57
24	BRS	78	4996587.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 17:57
25	BRS	16	6013948.pn. or 6235554.pn. or 5347159.pn. or 5432378.pn. or 5621375.pn. or 6151220.pn. or 6054760.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/15 18:17
26	BRS	7	6013948.pn. or 6235554.pn. or 5347159.pn. or 5432378.pn. or 5621375.pn. or 6151220.pn. or 6054760.pn.	USPAT	2001/08/15 18:17
27	BRS	274	(chip or die or IC) and (electrode or pad or connection) and "U" adj shaped adj (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/16 13:27
28	BRS	93	(chip or die or IC) and (electrode or pad or connection) and "C" adj shaped adj (wire or clip or conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/16 13:48

	Type	Hits	Search Text	DBs	Time Stamp
29	BRS	7	4780098.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/16 13:55
30	BRS	3	5139448.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/16 13:54
31	BRS	3	4780098.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/16 13:55
32	BRS	121	257/678 and (chip or die or IC) and (electrode or pad or connection) and (conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 11:32
33	BRS	0	257/678 and (chip or die or IC) and (electrode or pad or connection) and (C or U) adj shaped adj (conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 11:33
34	BRS	2	257/\$.ccls. and (chip or die or IC) and (electrode or pad or connection) and (C or U) adj shaped adj (conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 11:35
35	BRS	9	(chip or die or IC) and (electrode or pad or connection) and (C or U) adj shaped adj (conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 11:40
36	BRS	0	(chip or die or IC) and (electrode or pad or connection) and (C or U) adj shaped adj (conductive adj mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 11:42
37	BRS	0	(chip or die or IC) and (electrode or pad or connection) and shaped adj (conductive adj mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 11:43
38	BRS	20	(chip or die or IC) and (electrode or pad or connection) and (conductive adj mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 11:44

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39	BRS	27	257/678 and (chip or die or IC) and (electrode or pad or connection) and (wire or clip or conductive adj layer) and stack\$ and (conductive or wire or metal) adj layer and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 12:10
40	BRS	29	257/678 and (chip or die or IC) and (electrode or pad or connection) and stack\$ and (conductive or wire or metal) adj layer and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 12:11
41	BRS	87	257/777 and (chip or die or IC) and (electrode or pad or connection) and stack\$ and (conductive or wire or metal) adj layer and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 12:20
42	BRS	23	257/777 and (chip or die or IC) and (electrode or pad or connection) and stack\$ and (conductive or wire or metal) adj pattern and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/17 14:22